



V_{DS} 60V
 I_D 300mA
 $R_{DS(ON)}$ (at $V_{GS}=10V$) 2.5ohm
 $R_{DS(ON)}$ (at $V_{GS}=4.5V$) 3.0ohm
 Gate-Source ESD Rating Up to 2KV (HBM)

Trench Power MV MOSFET technology
 Voltage controlled small signal switch
 Low input Capacitance
 Fast Switching Speed
 Low Input / Output Leakage
 Moisture Sensitivity Level 1
 Epoxy Meets UL 94 V-0 Flammability Rating
 Halogen Free

DC/DC Converter
 Load Switch for Portable Devices

($T_A=25$ unless otherwise noted)

Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_A=25$ @ Steady State	I_D	300	mA
	$T_A=70$ @ Steady State		240	
Pulsed Drain Current ^A		I_{DM}	1.5	A
Total Power Dissipation @ $T_A=25$		P_D	250	mW
Thermal Resistance Junction-to-Ambient @ Steady State ^B		R_{JA}	500	/ W
Junction and Storage Temperature Range		T_J, T_{STG}	-55 +150	

(Example)





(T_J=25 unless otherwise noted)

Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±10	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1	1.5	2.5	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D =300mA		1.9	2.5	
		V _{GS} = 4.5V, I _D =200mA		2.0	3.0	
Diode Forward Voltage	V _{SD}	I _S =300mA, V _{GS} =0V			1.2	V
Maximum Body-Diode Continuous Current	I _S			300		mA
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =0.3A		0.13		S
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f=1MHZ		21		pF
Output Capacitance	C _{oss}			9		
Reverse Transfer Capacitance	C _{rss}			4		
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =30V, I _D =0.3A		1.22	2.4	g
Gate-Drain Mismatch						

v 7 \ S L F D O 3 H U I R U P D Q F H & K D U D F W H U L V W L F V

) L J X U H 2 X W S X W & K D U D F W H U L V W L F V

) Q V X W H H & K D W D F W H U L V W

) L J X U H & D S D F L W D Q F H & K D U D F W H U L V W L F V

) L J X U H * D W H & K D U

) L J X U H ' U D L Q 6 R X U F H R Q 5 H V L V W D Q F H) L J X U H

' U D L Q 6 R X U F H R Q 5

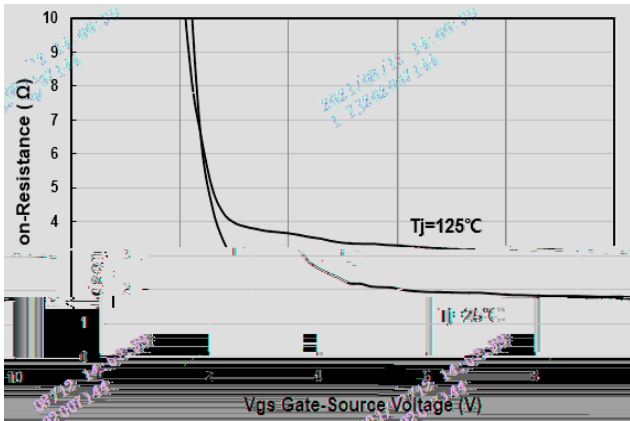


Figure7. On-Resistance vs V_{GS}

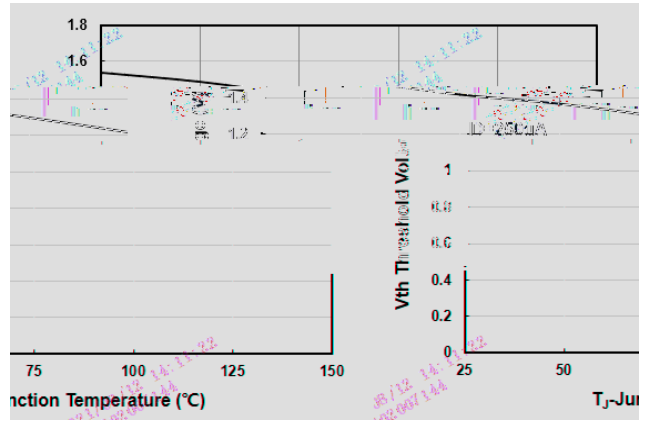


Figure8. Threshold Voltage vs Temperature

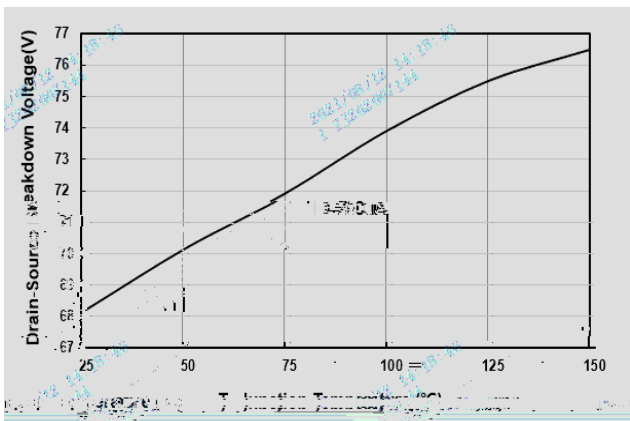


Figure9. Breakdown Voltage vs Temperature

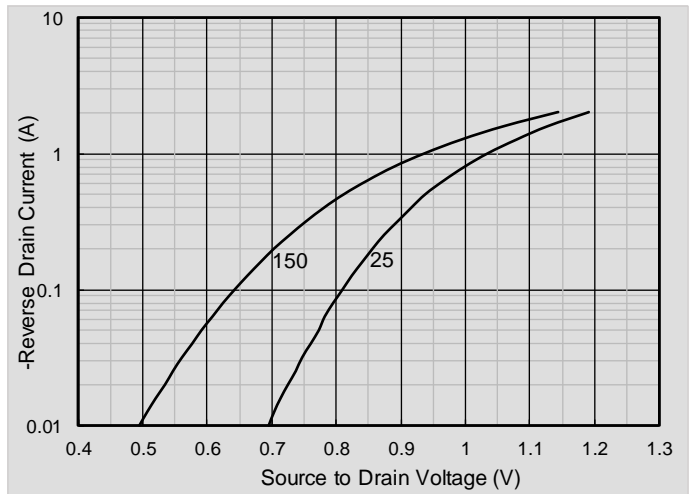


Figure 10. Forward characteristics of reverse diode

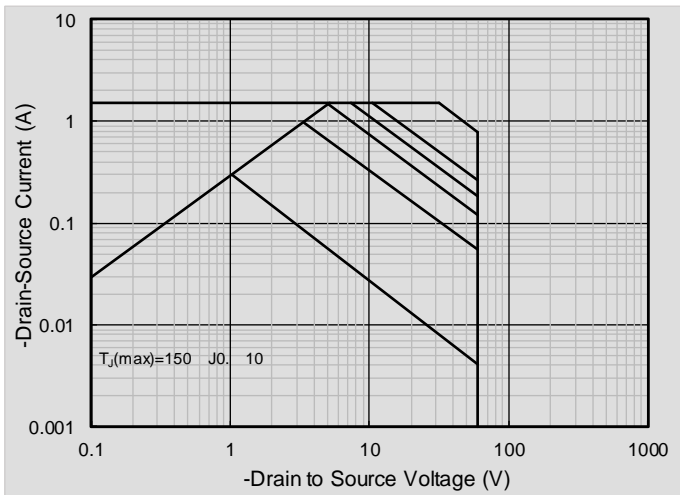


Figure 11. Safe Operation Area



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